



Final Product Change Notification

201605005F01

Issue Date: 30-Jun-2016
Effective Date: 14-Oct-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

- Introduction (additional) Cu-wire bonding various packages in ATBK (Phase VI)
- Replace Au (gold) wire with Cu (copper) wire in bonding process

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Introduction of Cu-wire bonding for SO20-24 and TSSOP24 packages in ATBK (Phase VI)

Details of this Change

Introduction of Cu-wire bonding for SO20-24 and TSSOP24 packages in ATBK (NXP Semiconductors Assembly & Test Plant Bangkok Thailand)

- Replace Au (gold) wire with Cu (copper) wire in bonding process

Why do we Implement this Change

- Capacity expansion on state of the art production tools
- Aligning with world technology trends, NXP starts to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties
- Increased environmental friendliness (eco-friendly)

Identification of Affected Products

- The changed products can be identified by backward traceability of their marking date code
- No change in product top side marking

Product Availability

Sample Information

Samples are available upon request

Limited samples are available upon request for high volume types in Logic sample store Nijmegen The Netherlands

Production

Planned first shipment 14-Oct-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Not applicable

Related Notifications

Notification	Issue Date	Effective Date	Title
201202018F0105-Dec-2012	05-Mar-2013		Cu-wire bonding in APB and ASEN for SO14-16 packages
201208012F0105-Dec-2012	05-Mar-2013		Cu-wire bonding in APB and ASEN for TSSOP14-16-20 packages
201304005F0117-Apr-2013	16-Jul-2013		Cu-wire bonding in APB and ASEN for SO14-16 packages (Phase II)
201304006F0117-Apr-2013	16-Jul-2013		Cu-wire bonding in APB and ASEN for TSSOP14-16-20 packages (Phase II)
201401003F0115-Jun-2014	13-Sep-2014		Cu-wire bonding in APB and ASEN for TSSOP48-56 packages (Phase III)
201409013F0109-Jan-2015	24-Apr-2015		Introduction of Cu-wire bonding for TSSOP5 and DHVQFN20 packages (Phase IV)
201412011F0111-Jan-2015	24-Apr-2015		Introduction of Cu-wire bonding for SO20 package (Phase IV)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 30-Jul-2016.

Remarks

- No change in data sheet, form, fit, function, quality or reliability anticipated
- No change in ordering part number / 12NC
- No change in product top side marking

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Emile Busink
Position PCN specialist - QA engineering Logic Products
e-mail address emile.busink@nxp.com

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Customer Focus, Passion to Win.

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